

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 14959
Application ID: 10063572
Title of Invention: WAFER LEVEL PACKAGING AND
CHIP STRUCTURE
First Named Inventor: Chi-Hsing Hsu
Domestic/Foreign Application: Domestic Application
Filing Date: null
Effective Receipt Date: 2002-05-03
Submission Type: Utility Patent Filing
Filing Type: new-utility
Confirmation Number: 0
Attorney Docket Number: 8289-US-PA
Digital Certificate Holder: cn=Belinda Lee, ou=Registered Attorneys, ou=Patent and
Trademark Office, ou=Department of Commerce, o=U.S.
Government, c=US
Certificate Message Digest: YUG1TywVS36WAX9NAACAhg==
Total Fees Authorized: \$864.0
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Credit Card Number: *****3109
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TRANSMITTAL FORM



Electronic Version 1.0.3

Stylesheet Version: 1.0

Attorney Docket
Number:

8289-US-
PA

Submission Type: Utility Patent
Filing

WAFER LEVEL PACKAGING AND CHIP STRUCTURE

First Named Inventor: Mr. Chi-Hsing Hsu

SUBMITTED BY

Name:	Miss BELINDA LEE
Registration Number:	46863
Electronic Signature Mark: /BL	Date Signed: 20020503

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Attached Files:

declaration	8289declaration1.tif
declaration	8289declaration2.tif
bibd-transmittal	8289usapds.xml
patent-assignments	8289usasgn.xml

fee-transmittal
specification

8289usfee.xml
8289usf.xml

Attached Image File(s):

8289declaration1.tif

8289declaration2.tif

8289usf.xml

Comments:

2025-07-27 10:00:00

FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

Patent fees are subject to annual revisions on or about October 1st of each year.

Large Entity

TOTAL FEES AUTHORIZED: \$ 864

BANK (CREDIT) CARD INFORMATION:

Credit Card Number: 3109
Expiration Date: 20030430
Authorized Name: LEE, HUAI-LU
Billing Address: 99999

BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 20	103	\$ 18	0	\$ 0
Independent Claims: 4	102	\$ 84	1	\$ 84

Subtotal For Extra Claims Fees: \$ 84

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40